

	Type	L #	Hits	Search Text	DBs
1	BRS	L1	1737	257/737.ccls.	US-PGPUB; USPAT; USOCR
2	BRS	L2	1647	257/738.ccls.	US-PGPUB; USPAT; USOCR
3	BRS	L3	1214	257/780.ccls.	US-PGPUB; USPAT; USOCR
4	BRS	L4	1857	257/787.ccls.	US-PGPUB; USPAT; USOCR
5	BRS	L5	2402	257/778.ccls.	US-PGPUB; USPAT; USOCR
6	BRS	L6	2087	257/774.ccls.	US-PGPUB; USPAT; USOCR
7	BRS	L7	2336	chip adj scale adj package	US-PGPUB; USPAT; USOCR
8	BRS	L8	72	wafer adj scale adj package	US-PGPUB; USPAT; USOCR
9	BRS	L9	245	L1 and (silicon with substrate) and resin and (electrode or pad or terminal) and (wiring or conduct\$3)	US-PGPUB; USPAT; USOCR
10	BRS	L12	229	L7 and (silicon with substrate) and resin and (electrode or pad or terminal) and (wiring or conduct\$3) and (opening or hole)	US-PGPUB; USPAT; USOCR
11	BRS	L13	8	L8 and (silicon with substrate) and resin and (electrode or pad or terminal) and (wiring or conduct\$3) and (opening or hole)	US-PGPUB; USPAT; USOCR

	Type	L #	Hits	Search Text	DBs
12	BRS	L11	96	L3 and (silicon with substrate) and resin and (electrode or pad or terminal) and (wiring or conduct\$3) and (opening or hole)	US-PGPUB; USPAT; USOCR
13	BRS	L14	1357	257/692.ccls.	US-PGPUB; USPAT; USOCR
14	BRS	L15	1914	257/773.ccls.	US-PGPUB; USPAT; USOCR
15	BRS	L16	1518	257/786.ccls.	US-PGPUB; USPAT; USOCR
16	BRS	L17	235	257/737.ccls.	EPO; JPO; DERWENT; IBM_TDB
17	BRS	L18	129	257/778.ccls.	EPO; JPO; DERWENT; IBM_TDB
18	BRS	L19	1790	257/787.ccls.	EPO; JPO; DERWENT; IBM_TDB
19	BRS	L20	1483	chip adj scale adj package	EPO; JPO; DERWENT; IBM_TDB
20	BRS	L21	23	wafer adj scale adj package	EPO; JPO; DERWENT; IBM_TDB
21	BRS	L10	155	L1 and (silicon with substrate) and resin and (electrode or pad or terminal) and (wiring or conduct\$3) and (opening or hole)	US-PGPUB; USPAT; USOCR